Cheng Zhuo

List of Publications by Year in descending order

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567281 580821 74 897 15 25 h-index citations g-index papers 74 74 74 458 docs citations times ranked citing authors all docs

| # | Article | IF | CITATIONS |
|----|--|------|-----------|
| 1 | LIAS: A Lightweight Incentive Authentication Scheme for Forensic Services in IoV. IEEE Transactions on Automation Science and Engineering, 2023, 20, 805-820. | 5.2 | 4 |
| 2 | Computing-In-Memory Using Ferroelectrics: From Single- to Multi-Input Logic. IEEE Design and Test, 2022, 39, 56-64. | 1.2 | 5 |
| 3 | Senputing: An Ultra-Low-Power Always-On Vision Perception Chip Featuring the Deep Fusion of Sensing and Computing. IEEE Transactions on Circuits and Systems I: Regular Papers, 2022, 69, 232-243. | 5.4 | 28 |
| 4 | A novel analytic approach for outcome prediction in diffuse large B-cell lymphoma by [18F]FDG PET/CT. European Journal of Nuclear Medicine and Molecular Imaging, 2022, 49, 1298-1310. | 6.4 | 22 |
| 5 | Improving Fault Tolerance for Reliable DNN Using Boundary-Aware Activation. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2022, 41, 3414-3425. | 2.7 | 8 |
| 6 | ANT-UNet: Accurate and Noise-Tolerant Segmentation for Pathology Image Processing. ACM Journal on Emerging Technologies in Computing Systems, 2022, 18, 1-17. | 2.3 | 1 |
| 7 | Application of Deep Learning in Back-End Simulation: Challenges and Opportunities. , 2022, , . | | 8 |
| 8 | VirtualSync+: Timing Optimization with Virtual Synchronization. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2022, , 1-1. | 2.7 | 0 |
| 9 | Magnetic Core TSV-Inductor Design and Optimization for On-chip DC-DC Converter. ACM Transactions on Design Automation of Electronic Systems, 2022, 27, 1-23. | 2.6 | 4 |
| 10 | DeU-Net 2.0: Enhanced deformable U-Net for 3D cardiac cine MRI segmentation. Medical Image Analysis, 2022, 78, 102389. | 11.6 | 15 |
| 11 | A Resource-Efficient Deep Learning Framework for Low-Dose Brain Pet Image Reconstruction and Analysis. , 2022, , . | | 4 |
| 12 | OPACT: Optimization of Approximate Compressor Tree for Approximate Multiplier., 2022,,. | | 1 |
| 13 | Robustness of Neuromorphic Computing with RRAM-based Crossbars and Optical Neural Networks. , 2021, , . | | 1 |
| 14 | Energy-Aware Designs of Ferroelectric Ternary Content Addressable Memory., 2021,,. | | 13 |
| 15 | Joint Sparsity with Mixed Granularity for Efficient GPU Implementation. , 2021, , . | | O |
| 16 | Impact of Supply Noise on Nano-Meter VLSI Design: Hard or Soft Threshold?., 2021,,. | | 0 |
| 17 | On the Reliability of In-Memory Computing: Impact of Temperature on Ferroelectric TCAM. , 2021, , . | | 15 |
| 18 | Brain metabolic characteristics distinguishing typical and atypical benign epilepsy with centro-temporal spikes. European Radiology, 2021, 31, 9335-9345. | 4.5 | 7 |

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| 19 | A Reconfigurable Multiplier for Signed Multiplications with Asymmetric Bit-Widths. ACM Journal on Emerging Technologies in Computing Systems, 2021, 17, 1-16. | 2.3 | 3 |
| 20 | RCoNet: Deformable Mutual Information Maximization and High-Order Uncertainty-Aware Learning for Robust COVID-19 Detection. IEEE Transactions on Neural Networks and Learning Systems, 2021, 32, 3401-3411. | 11.3 | 35 |
| 21 | Cross-layer Design for Computing-in-Memory. , 2021, , . | | 2 |
| 22 | A Physical-Aware Framework for Memory Network Design Space Exploration. , 2021, , . | | 0 |
| 23 | A deep learning framework for 18F-FDG PET imaging diagnosis in pediatric patients with temporal lobe epilepsy. European Journal of Nuclear Medicine and Molecular Imaging, 2021, 48, 2476-2485. | 6.4 | 20 |
| 24 | Bayesian Inference Based Robust Computing on Memristor Crossbar. , 2021, , . | | 13 |
| 25 | Reliable Memristor-based Neuromorphic Design Using Variation- and Defect-Aware Training. , 2021, , . | | 9 |
| 26 | ICCAD Tutorial Session Paper Ferroelectric FET Technology and Applications: From Devices to Systems. , 2021, , . | | 8 |
| 27 | Noise-Aware DVFS for Efficient Transitions on Battery-Powered IoT Devices. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 1498-1510. | 2.7 | 62 |
| 28 | Dynamic Frequency Scaling Aware Opportunistic Through-Silicon-Via Inductor Utilization in Resonant Clocking. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 281-293. | 2.7 | 14 |
| 29 | Energy-Efficient Real-Time UAV Object Detection on Embedded Platforms. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 3123-3127. | 2.7 | 29 |
| 30 | Early-Stage Planning of Switched-Capacitor Converters in a Heterogeneous Chip. IEEE Access, 2020, 8, 85900-85911. | 4.2 | 1 |
| 31 | Eva-CiM: A System-Level Performance and Energy Evaluation Framework for Computing-in-Memory Architectures. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2020, 39, 5011-5024. | 2.7 | 27 |
| 32 | FeCAM: A Universal Compact Digital and Analog Content Addressable Memory Using Ferroelectric. IEEE Transactions on Electron Devices, 2020, 67, 2785-2792. | 3.0 | 75 |
| 33 | A Reconfigurable Approximate Multiplier for Quantized CNN Applications. , 2020, , . | | 11 |
| 34 | Nonvolatile and Energy-Efficient FeFET-Based Multiplier for Energy-Harvesting Devices., 2020,,. | | 8 |
| 35 | Modeling and Benchmarking Computing-in-Memory for Design Space Exploration. , 2020, , . | | 11 |
| 36 | Countering variations and thermal effects for accurate optical neural networks. , 2020, , . | | 16 |

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| 37 | Optimally approximated and unbiased floating-point multiplier with runtime configurability. , 2020, , . | | 16 |
| 38 | Analog Content Addressable Memory using Ferroelectric: A Case Study of Search-in-Memory. , 2020, , . | | 0 |
| 39 | From Layout to System: Early Stage Power Delivery and Architecture Co-Exploration. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2019, 38, 1291-1304. | 2.7 | 41 |
| 40 | Single-Inductor–Multiple-Tier Regulation: TSV-Inductor-Based On-Chip Buck Converters for 3-D IC Power Delivery. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2019, 27, 2305-2316. | 3.1 | 18 |
| 41 | A Low-Computational Complexity System for EEG Signals Compression and Classification. , 2019, , . | | 0 |
| 42 | A Multicore Chip Load Model for PDN Analysis Considering Voltage–Current-Timing Interdependency and Operation Mode Transitions. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1669-1679. | 2.5 | 5 |
| 43 | A Cross-Layer Framework for Temporal Power and Supply Noise Prediction. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2019, 38, 1914-1927. | 2.7 | 2 |
| 44 | Optimizing the Energy Efficiency of Power Supply in Heterogeneous Multicore Chips with Integrated Switched-Capacitor Converters., 2019,,. | | 4 |
| 45 | Power Delivery Resonant Virus: Concept and Applications. , 2019, , . | | 0 |
| 46 | Revisiting EAVP for Power Delivery Decoupling Optimization., 2019,,. | | 0 |
| 47 | The Impact of Emerging Technologies on Architectures and System-level Management: Invited Paper. , 2019, , . | | 0 |
| 48 | Earlyâ€stage microfluidic network design framework using graph sparsificiation based optimisation. Electronics Letters, 2019, 55, 1034-1037. | 1.0 | 0 |
| 49 | Floating Random Walk-Based Capacitance Simulation Considering General Floating Metals. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2018, 37, 1711-1715. | 2.7 | 16 |
| 50 | Modeling and optimization of magnetic core TSV-inductor for on-chip DC-DC converter. , 2018, , . | | 7 |
| 51 | A Multi-Level-Optimization Framework for FPGA-Based Cellular Neural Network Implementation. ACM Journal on Emerging Technologies in Computing Systems, 2018, 14, 1-17. | 2.3 | 19 |
| 52 | A physics-aware methodology for equivalent circuit model extraction of TSV-inductors. The Integration VLSI Journal, 2018, 63, 160-166. | 2.1 | 1 |
| 53 | Efficient segmentation method using quantised and nonâ€linear CeNN for breast tumour classification. Electronics Letters, 2018, 54, 737-738. | 1.0 | 8 |
| 54 | CN-SIM: A cycle-accurate full system power delivery noise simulator. , 2017, , . | | 1 |

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| 55 | TSV inductor optimization and its design implication. , 2017, , . | | 1 |
| 56 | Novel LC resonant clocking for 3D IC using TSV-inductor and capacitor. , 2017, , . | | 2 |
| 57 | Electrical-thermal co-analysis of through silicon via with equivalent circuit model. , 2017, , . | | 5 |
| 58 | A novel cross-layer framework for early-stage power delivery and architecture co-exploration. , 2016, | | 9 |
| 59 | A cross-layer framework for early-stage full chip oxide breakdown reliability analysis. , 2016, , . | | 0 |
| 60 | Silicon-Validated Power Delivery Modeling and Analysis on a 32-nm DDR I/O Interface. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2015, 23, 1760-1771. | 3.1 | 11 |
| 61 | A Cross-Layer Approach for Early-Stage Power Grid Design and Optimization. ACM Journal on Emerging Technologies in Computing Systems, 2015, 12, 1-20. | 2.3 | 7 |
| 62 | On the Efficacy of Through-Silicon-Via Inductors. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2015, 23, 1322-1334. | 3.1 | 59 |
| 63 | Opportunistic through-silicon-via inductor utilization in LC resonant clocks: Concept and algorithms. , $2014, \ldots$ | | 11 |
| 64 | Early-Stage Power Grid Design. , 2014, , . | | 5 |
| 65 | Novel Through-Silicon-Via Inductor-Based On-Chip DC-DC Converter Designs in 3D ICs. ACM Journal on Emerging Technologies in Computing Systems, 2014, 11, 1-14. | 2.3 | 37 |
| 66 | Through-silicon-via inductor: Is it real or just a fantasy?. , 2014, , . | | 24 |
| 67 | A Statistical Framework for Post-Fabrication Oxide Breakdown Reliability Prediction and Management. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2013, 32, 630-643. | 2.7 | 3 |
| 68 | A silicon-validated methodology for power delivery modeling and simulation. , 2012, , . | | 17 |
| 69 | Process Variation and Temperature-Aware Full Chip Oxide Breakdown Reliability Analysis. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2011, 30, 1321-1334. | 2.7 | 20 |
| 70 | In-package P/G planes analysis and optimization based on transmission matrix method. Journal of Zhejiang University: Science A, 2008, 9, 849-857. | 2.4 | 0 |
| 71 | Power Grid Analysis and Optimization Using Algebraic Multigrid. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2008, 27, 738-751. | 2.7 | 45 |
| 72 | A statistical approach for full-chip gate-oxide reliability analysis. , 2008, , . | | 18 |

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| 73 | Modeling, optimization and control of rotary traveling-wave oscillator. IEEE/ACM International Conference on Computer-Aided Design, Digest of Technical Papers, 2007, , . | 0.0 | 3 |
| 74 | Fast Decap Allocation Based on Algebraic Multigrid. IEEE/ACM International Conference on Computer-Aided Design, Digest of Technical Papers, 2006, , . | 0.0 | 2 |